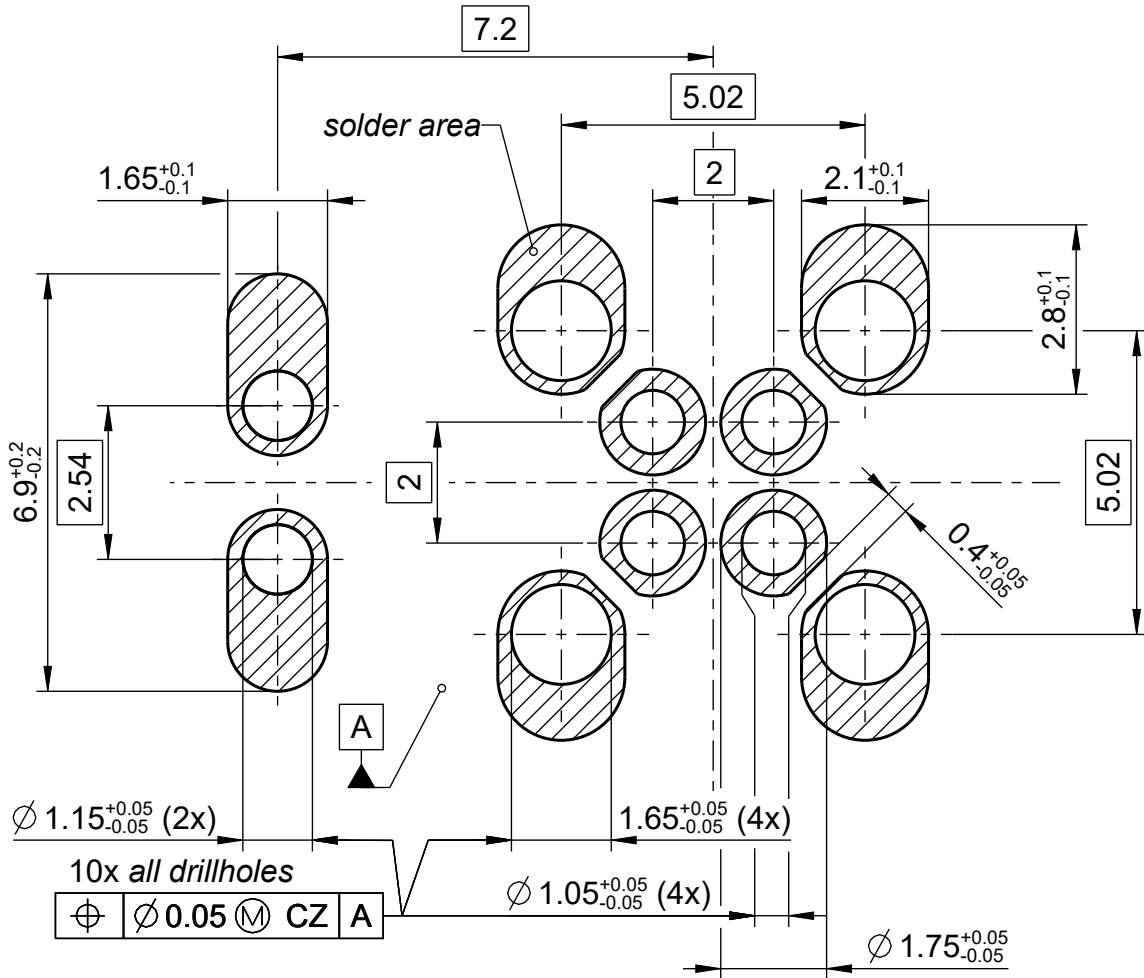


1) Alle schraffierten Bohrungen kontaktieren mit Restrings auf der Rueckseite durch. (Restringsbreite min. 0.2mm)  
 All hatched holes plate through inclusive pads on the backside. (padwith min. 0.2mm)



Die angegebenen Masse und Toleranzen sind nur Empfehlungen.  
 The stated dimensions are only recommendations.

A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.  
 Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.  
 In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

PD\_FB\_01

-METRIC-



ISO-Projektion  
 Methode 1

<b>Rosenberger</b>		general tolerance		scale: 8:1 ( )	weight[g]:
		ISO 2768	RN 006-01		surface[mm <sup>2</sup> ]:
vertraulich / confidential		mH		material:	
		dimensions <0,5 and symmetry			
		date		title:	
		drawn	28.02.2018	Leiterplatten-Layout	
		check	03.05.2021	PCB layout	
		appr.	05.05.2021		
		dimensioning incl. plating		drawing-no.:	
		Size ISO 14405 (E)		MB_728	
		Tolerancing ISO 8015		sheet: 1	
rev. change-no		name		of: 1	
date		date		remarks: .MB_521	

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